For new designs it is highly recommended to implement the following changes for the ITE6801 part:

1) Change OVDD to 3.3V
2) Add HVdden & PCSDA to 3.3V (Further changes to other parts in the design might be required based on interface design and logic levels)

Audio outputs have some optional configurations, please refer to datasheet for details.
EXTERNAL POWER INPUT

VFB = 1.205V
VOUT = 1.8V

5V 5A MAX
Revisions

Rev. 0.0 : Development version

Rev. A.0 : Initial Release
- R14 changed to 47k, C45 changed to 2200pF
- U2 pin 2 disconnected from 3.3V and connected to 1.8V
- Add net SCL_IFP to IIC0_SCL
- Add net SDA_IFP to IIC0_SDA

Rev. B.0 : Do not install unused connectors, etc.
- VR1, J9, J13
Rev. B.1 : Added note for future designs to ITE6801 page
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